

HSF

NOTES:

Current Rating:3.0AMP
Contact Resistance:30milliohm Max
Withstand Voltage:1000V AC
Insulation Resistance:1000Megohm Min
Operation Temperature:-55℃ to +105℃

Contact Material: Brass
Contact Plating: Au and Sn over Ni
Fixing Material: Phosphor Bronze
Fixing Plating: Sn over Ni
Insulation Material: PBT+30% G.F(UL94V-0)

Ordering Information

3410-3 XX X MR SX X A X

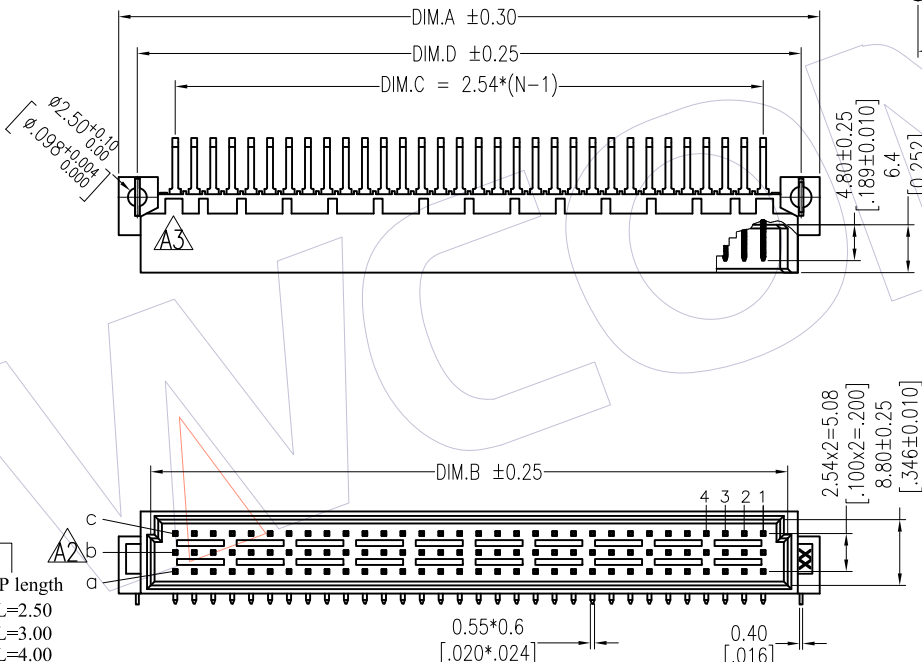
No.of Pins Per Row
10P
16P
32P

Rows with contacts
A=a+b+c
B=a+b
C=a+c
D=a

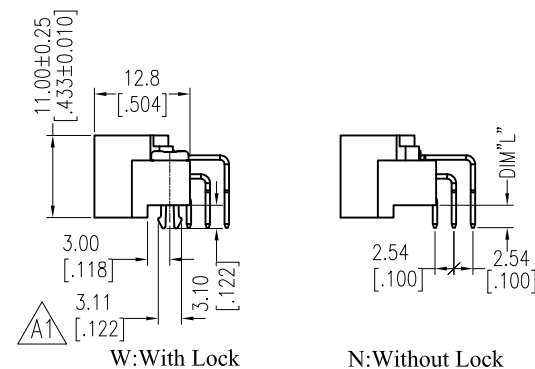
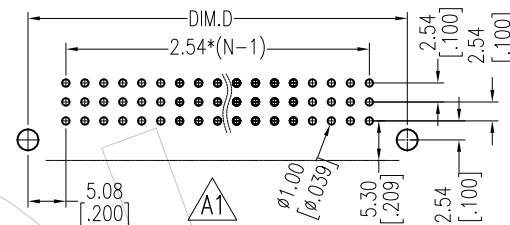
Contact Plating:
S0=Gold Flash/Tin
S1=3u"Gold/Tin
S3=10u"Gold/Tin
S4=15u"Gold/Tin
S5=30u"Gold/Tin
SN=Tin

Packing:
A=Tray
W=With Lock
N=Without Lock

DIP length
1:L=2.50
2:L=3.00
3:L=4.00
4:L=4.57



Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE ± 0.05)



C	96	3	32	93.90	85.30	78.74	88.90
C/2	48	3	16	53.26	44.66	38.10	48.26
C/3	30	3	10	38.02	29.42	22.86	33.02
TYPE	POS.	ROWS	N	DIM.A	DIM.B	DIM.C	DIM.D

A3	2015/01/15	Modify	A3	OPERATION	DRAW	DATE	SCALE	FIT	PART NO.	
A2	2014/11/05	a1,b1,c1---a,b,c	A2	X.X ± 0.40	JYHuang	2015/01/15	UNIT	mm	3410-3XXXMRXXXAX	
A1	2014/08/12	Modify		X.XX ± 0.25	CHECK	DATE	SIZE	A4	TITLE:	
AO	2014/05/29	NEW		X.XXX ± 0.15			SHEET	1/1	2.54PITCH DIN 41612	
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	Angle $\pm 3^\circ$	APPROVE	DATE	PROJ.	Customer NO.		
				DIM TOL						